

#### **Description**

The DMN2005UFG uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

 $V_{DS} = 20V I_{D} = 60A$ 

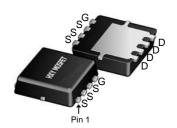
 $R_{DS(ON)} < 5m\Omega$  @  $V_{GS}=4.5V$ 

#### **Application**

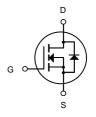
Battery protection

Load switch

Uninterruptible power supply



DFN3X3-8L



N-Channel MOSFET

### **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
DMN2005UFG	DFN3X3-8L	HXY MOSFET	5000

#### Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V <sub>D</sub> s	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	60	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	33	Α
Ілм	Pulsed Drain Current <sup>2</sup>	220	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	46	mJ
las	Avalanche Current	25	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	15	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R <sub>0</sub> JA	Thermal Resistance Junction-ambient <sup>1</sup>	62	°C/W
R <sub>θ</sub> Jc	Thermal Resistance Junction-Case <sup>1</sup>	4.5	°C/W

### N-Channel Enhancement Mode MOSFET

# **Electrical Characteristics** (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	0.4	0.7	1.1	V
Ъ	Static Drain-Source on-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A	-	4.0	5	
$R_{DS(on)}$		V <sub>GS</sub> =2.5V, I <sub>D</sub> =20A	-	6.0	9	mΩ
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f = 1.0MHz	-	2500	-	pF
Coss	Output Capacitance		-	407	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	386	-	pF
Qg	Total Gate Charge	V <sub>DS</sub> =10V, I <sub>D</sub> =30A, V <sub>GS</sub> =4.5V	-	32	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	3	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	11	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	14 4014	-	17	-	ns
t <sub>r</sub>	Turn-on Rise Time	V <sub>DS</sub> =10V,	-	49	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	$I_D$ =30A, $R_{GEN}$ =3 $\Omega$ , $V_{GS}$ =4.5 $V$	-	74	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	26	-	ns
	Maximum Continuous Drain to Source	e Diode Forward			7.5	۸
Is	Current		-	-	75	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	300	Α
\/	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0V, I <sub>S</sub> =30A				1.0	V
$V_{SD}$			_	_	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition: TJ=25  $^{\circ}\text{C}$  , VDD=10V, VG=4.5V, L=0.5mH, RG=25  $^{\Omega}$  , IAS=15A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



# **Typical Performance Characteristics**

Figure 4. Output Characteristics

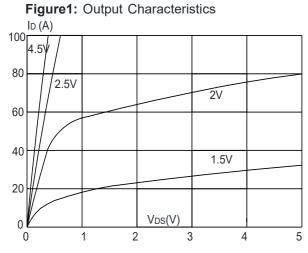


Figure 2: Typical Transfer Characteristics

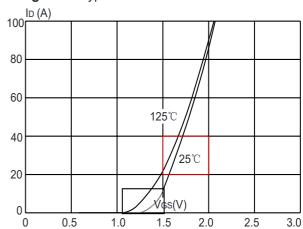
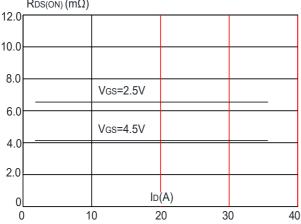


Figure 3:On-resistance vs. Drain Current  $\text{RDS}(\text{ON}) \left( m\Omega \right)$ 



**Figure 4**: Body Diode Characteristics Is(A)

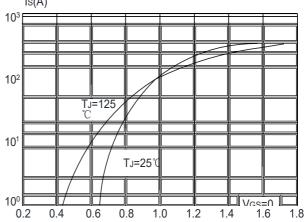


Figure 5: Gate Charge Characteristics

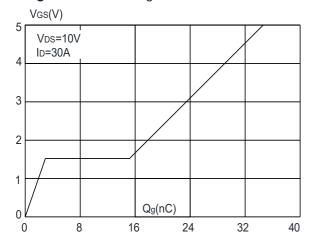
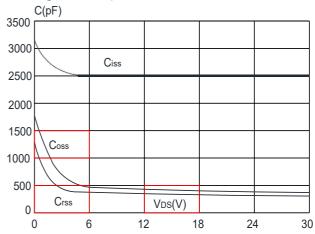


Figure 6: Capacitance Characteristics





**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

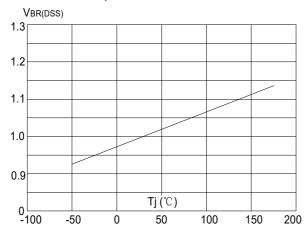
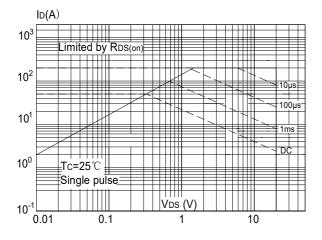
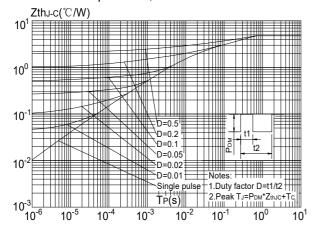


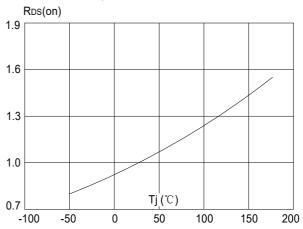
Figure 9: Maximum Safe Operating Area



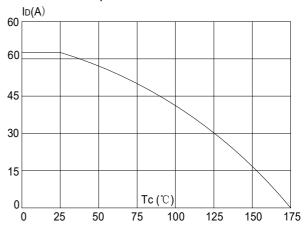
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature

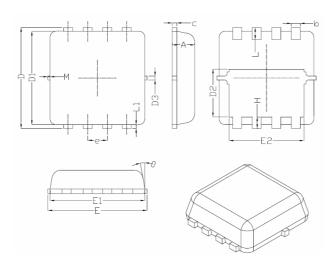


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature





## **DFN3X3-8L Package Information**



C. mak a l	Dimensions In Millimeters		
Symbol	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
С	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
Н	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10 <sup>°</sup>	12 <sup>°</sup>



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